



Dear Valued Customer

Doc. No.: 2222001
Issue date: September 1, 2022

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General Manager

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ROHM Co., Ltd.

Notification of Product/Process Change

This is an announcement of change(s) to the process of the products currently supplied by ROHM Co., Ltd.

We request your acknowledgement of the receipt of this notification within the given period.

Please provide your reply by September 1, 2023

Title of change	Wafer Diameter Change, Wafer Process Production Site Change, Assembly Process changed to In-house Manufacturing for 3rd Generation SiC MOSFET (TO247-4 Package) SCT3****R Series [PCN No.2222001]		
Affected product(s)	Manufacturer part number		Customer part number
	SCT3□□□□RC14		
Detailed description of change	Now		After
	<ul style="list-style-type: none"> ·On-board SiC chip's wafer diameter:4inch ·Front-end manufacturing plants : ROHM Apollo Co., Ltd. Chikugo Plant ·Assembly manufacturing plants :ATX SEMICONDUCTOR(WEIHAI) CO.,LTD. ·P/N:SCT3□□□□RC14 		<ul style="list-style-type: none"> ·On-board SiC chip's wafer diameter:6inch ·Front-end manufacturing plants : Lapis Semiconductor Co., Ltd. Miyazaki Plant ·Assembly manufacturing plants :ROHM INTEGRATED SYSTEMS (THAILAND) CO., LTD. ·P/N:SCT3□□□□RC15
Reason for change	To expand production capacity.		
Anticipated impact on quality	There is no difference in reliability and electrical characteristics.		
Identification of change	It can be identified by package outline and marking code.		
Planned first ship date :	April 1, 2023	Sample available schedule :	Within 1.5 months from request
Attachments (data, report)	yes	4M 2222001-2_4ME	Rbl 2222001-3_Rbl
Comments			

		Reply date	
Customer reply	<input type="checkbox"/> 1. Approved. <input type="checkbox"/> 2. Accepted with conditions. <input type="checkbox"/> 3. Rejected.		
Condition for approval / reason for rejection			
Comments			
Customer company name			
Customer signature	Department		
Customer signature	Department		